

In the Specification:

Please replace the paragraph beginning on page 19, line 29 and extending to page 20, line 7, with the following:

As the wafer moves toward the engagement end 118 of the top track, the dislodgement leaf spring 129 of the wafer stay 125 contacts the wafer, as shown in FIG. 15(c). The spring 129 pushes the wafer downward into the bottom track 120. It can be seen in FIG. 15(c) that the pusher 135 is beneath the wafer. Once the wafer is disposed within the introduction opening 121 of the bottom track ~~570~~ 120, the end 136 of the pusher can then contact the advancement notch 23 of the wafer. The advancer/pusher mechanism 92 is propelled toward the discharge end 64 of the apparatus, so the pusher end 136 continues to push the wafer until it is firmly positioned at the bottom of the distraction stack.

Please replace the paragraph on page 17 spanning lines 3-15, with the following:

Details of the track assembly 63 can be seen in FIG. 13. In the preferred embodiment, the track assembly 63 includes a top track 115, a bottom track 120 and a wafer stay 125. The track assembly 63 is mounted to the wafer cartridge 100, which is mounted to the distal end 69 of the advancement gun 65. In one embodiment, the end walls 61a of the wafer cartridge housing 100 define a slot 103 into which the track assembly 63 is mounted. The top track includes a wafer insertion opening 116 that is disposed immediately beneath the wafer stack 101 when the track assembly is mounted within the slot 103. The top track further defines a wafer channel 117 along its length that provides the initial path along which a succession of wafers can be advanced to the discharge end 64 (FIG. 7) of the apparatus. The end 118 of the top track is configured to engage the bottom track at a location 121. Preferably, the end 118 is configured at portion 119 to wrap around the bottom track at this location and can be suitably affixed so that the track assembly 63 is substantially rigid.